

Figure 1. A Bluetooth module



Figure 2 50 pieces chips in an anti-static blister package

2. Feature

- Wireless transceiver
 - Sensitivity (Bit error rate) can reach -80dBm.
 - > The change range of output's power: -4 +6dBm.
- Function description (perfect Bluetooth solution)
 - > Has an EDR module; and the change range of modulation depth: 2Mbps 3Mbps.
 - Has a build-in 2.4GHz antenna; user needn't test antenna.

- ➢ Has the external 8Mbit FLASH
- Can work at the low voltage (3.1V~4.2V). The current in pairing is in the range of 30~40mA. The current in communication is 8mA.
- > PIO control can be switched.
- → Has the standard HCI Port (UART or USB)
- > The USB protocol is Full Speed USB1.1, and compliant with 2.0.
- > This module can be used in the SMD.
- ➢ It's made through RoHS process.
- > The board PIN is half hole size.
- > Has a 2.4GHz digital wireless transceiver.
- Bases at CSR BC04 Bluetooth technology.
- ➤ Has the function of adaptive frequency hopping.
- Small (27mm $\times 13$ mm $\times 2$ mm).
- > Peripheral circuit is simple.
- ▶ It's at the Bluetooth class 2 power level.
- Storage temperature range: -40 °C 85 °C, operating temperature range: -25 °C +75 °C
- Any wave inter Interference: 2.4MHz, the power of emitting: 3 dBm.
- Bit error rate: 0. Only the signal decays at the transmission link, bit error may be produced. For example, when RS232 or TTL is being processed, some signals may decay.
- Low power consumption
- Has high-performance wireless transceiver system
- Low Cost
- Application fields:
 - Bluetooth Car Handsfree Device
 - Bluetooth GPS
 - Bluetooth PCMCIA, USB Dongle
 - Bluetooth Data Transfer
 - Software
 - > CSR

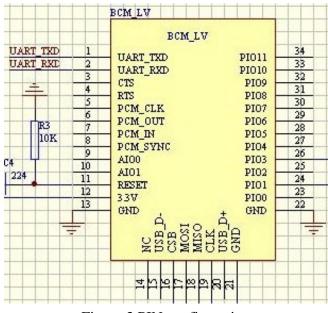


Figure 3 PIN configuration

The PINs at this block diagram is same as the physical one.

PIN Name	PIN #	Pad type	Description	Note
GND	13 21 22	VSS	Ground pot	
1V8	14	VDD	Integrated 1.8V (+) supply with On-chip linear regulator output within 1.7-1.9V	
VCC	12	3.3V		
AIO0	9	Bi-Directional	Programmable input/output line	
AIO1	10	Bi-Directional	Programmable input/output line	
PIO0	23	Bi-Directional RX EN	Programmable input/output line, control output for LNA(if fitted)	
PIO1	24	Bi-Directional TX EN	Programmable input/output line, control output for PA(if fitted)	
PIO2	25	Bi-Directional	Programmable	

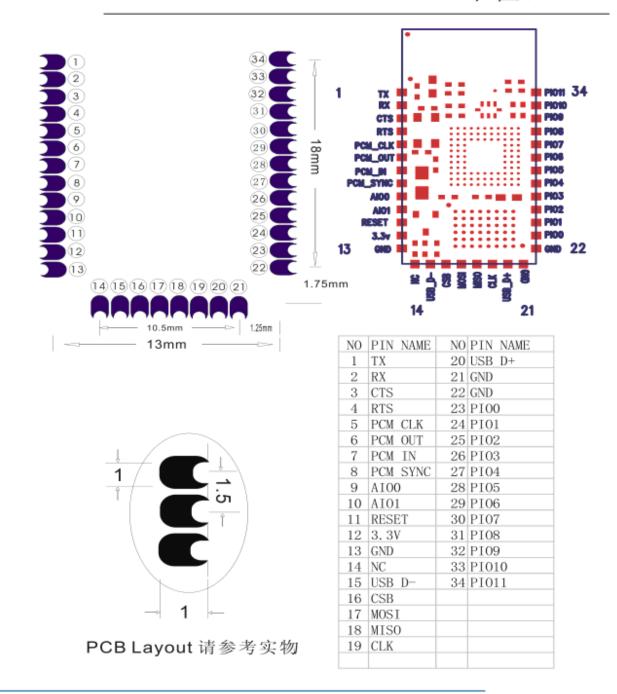
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PIO3	26	Bi-Directional	Programmable		
	_		input/output line		
PIO4	27	Bi-Directional	Programmable		
		Di Directionar	input/output line		
PIO5	28	Bi-Directional	Programmable		
			input/output line		
PIO6	29	Bi-Directional	Programmable	CLK_REQ	
1100			input/output line	·{	
PIO7	30	Bi-Directional	Programmable	CLK_OUT	
1107	50		input/output line	0211_001	
PIO8	31	Bi-Directional	Programmable		
1100	51	Di-Directional	input/output line		
PIO9	32	Bi-Directional	Programmable		
FIO9		DI-Directional	input/output line		
PIO10	33	Bi-Directional	Programmable		
PIOIO			input/output line		
DIO11	34	Bi-Directional	Programmable		
PIO11			input/output line		
	11	CMOS Input with weak			
RESETB		internal pull-down			
		-			
UART_RTS	4	CMOS output, tri-stable with	UART request to send,		
		weak internal pull-up	active low		
UART_CTS	3	CMOS input with weak	UART clear to send, active		
UARI_CIS		internal pull-down	low		
UART_RX	2	CMOS input with weak	UART Data input		
0/1101_10/1	<u>ک</u>	internal pull-down			
HART TX	1	CMOS output, Tri-stable	UART Data output		
UART_TX	1	with weak internal pull-up			
SPI_MOSI	17	CMOS input with weak	Serial peripheral interface		
		internal pull-down	data input		
	16	CMOS input with weak internal pull-up	Chip select for serial		
SPI_CSB			peripheral interface, active		
			low		
SPI_CLK	19	CMOS input with weak	Serial peripheral interface		

	1		1	1
SPI_MISO	18	CMOS input with weak internal pull-down	Serial peripheral interface data Output	
USB	15	Bi-Directional		
USB_+	20	Bi-Directional		
1.8V	14		1.8V external power supply input	Default : 1.8V internal power supply.
PCM_CLK	5	Bi-Directional		
PCM_OUT	6	CMOS output		
PCM_IN	7	CMOS Input		
PCM_SYNC	8	Bi-Directional		

LINVOR BLUE T www.linvor.com

LV-BC-2.0

单位: mm



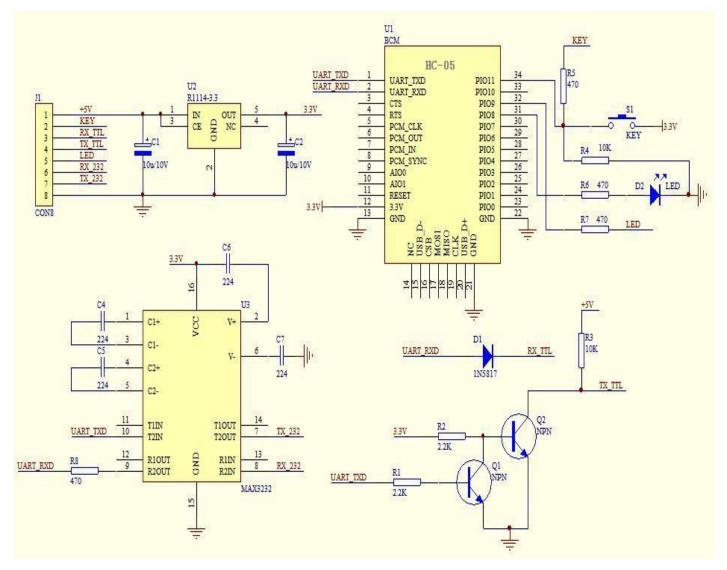


Figure 5 Block diagram

6. Debugging device

6.1 Device

PC, hardware, 3G, 3G Frequency Counter (SP3386), 3.15V DC power supply, Shielding, Bluetooth Test box.

6.2 Software

<u>2</u> .	RF O/P Power	-6	2	4	dBm
<u>3.</u>	Step size of Power control	2		8	dB
<u>4.</u>	Freq. Offset (Typical Carrier freq.)	-75		75	KHz
<u>5.</u>	Carrier Freq. drift (Hopping on, drift rate/50uS)	-20		20	KHz
	1 slot packet	-25		25	KHz
	3 slot packet	-40		-40	KHz
6.	Average Freq. Deviations (Hopping off, modulation)	140		175	KHz
	Freq. Deviation	115			KHz
	Ratio of Freq. Deviation	0.8			
<u>7</u> .	Receive Sensitivity @<0.1% BER(Bit error rate)	-83			dBm

8. Test diagram

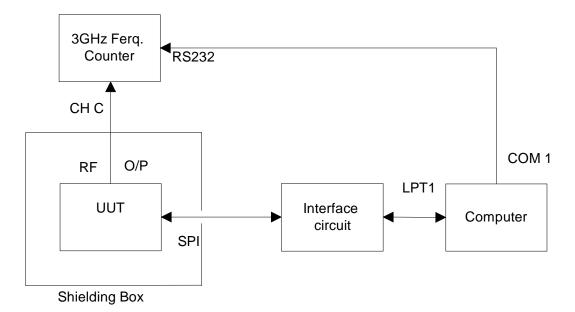


Fig 1. Programming and Freq. Alignment

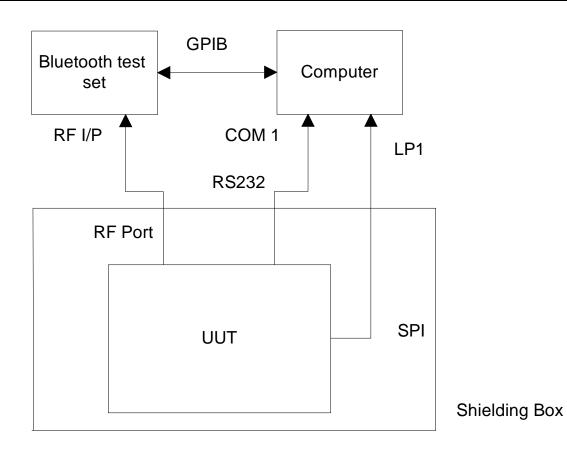


Fig 2 RF parameter Test Procedure

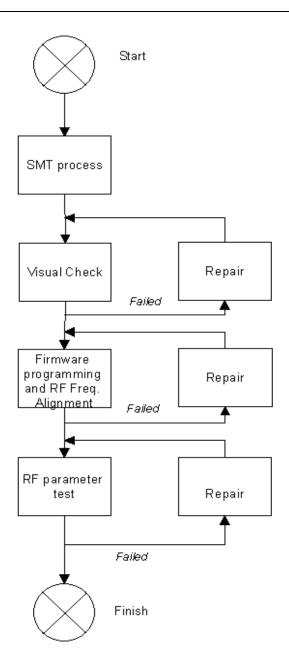


Fig 3 Assemble/Alignment/Testing Flow Chart